MOSFET – Single, N-Channel, Small Signal, SOT-23 30 V, 0.56 A

Features

- Low Gate Voltage Threshold (V_{GS(TH)}) to Facilitate Drive Circuit Design
- Low Gate Charge for Fast Switching
- ESD Protected Gate
- SOT-23 Package Provides Excellent Thermal Performance
- Minimum Breakdown Voltage Rating of 30 V
- NVR Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

Applications

- Notebooks:
 - Level Shifters
 - Logic Switches
 - Low Side Load Switches
- Portable Applications

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parame	Parameter				
Drain-to-Source Voltage	V_{DSS}	30	V		
Gate-to-Source Voltage			V_{GS}	±20	V
Continuous Drain	Steady	T _A = 25°C	I _D	0.5	Α
Current (Note 1)	State	T _A = 85°C		0.37	
Power Dissipation (Note 1)	Steady State		P _D	0.69	W
Continuous Drain	t < 10 s	T _A = 25°C	I _D	0.56	Α
Current (Note 1)		T _A = 85°C		0.40	
Power Dissipation (Note 1)	t < 5 s		P _D	0.83	W
Pulsed Drain Current	t _p =	: 10 μs	I _{DM}	1.7	Α
Operating Junction and Storage Temperature			T _J , Tstg	–55 to 150	°C
Source Current (Body Dio	Is	1.0	Α		
Lead Temperature for Sol (1/8" from case for 10 s)	dering Pur	poses	TL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

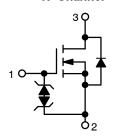


ON Semiconductor®

www.onsemi.com

V _{(BR)DSS}	R _{DS(on)} TYP	I _D MAX
30 V	1.0 Ω @ 4.0 V	0.56 A
30 V	1.5 Ω @ 2.5 V	

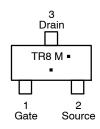
N-Channel



MARKING DIAGRAM/ PIN ASSIGNMENT



SOT-23 CASE 318 STYLE 21



TR8 = Specific Device Code

M = Date Code = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
NTR4003NT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel
NTR4003NT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel
NVR4003NT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Ambient - Steady State (Note 1)	$R_{\theta JA}$	180	°C/W
Junction-to-Ambient - t < 10 s (Note 1)	$R_{\theta JA}$	150	
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	300	

Surface-mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [1 oz] including traces).
 Surface-mounted on FR4 board using the minimum recommended pad size.

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified)

Parameter	Symbol	Test Cond	lition	Min	Тур	Max	Units
OFF CHARACTERISTICS			•		•		•
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D$	= 100 μΑ	30			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J				40		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V, V_{DS} = 30 V$	T _J = 25°C			1.0	μА
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS}$	s = ±10 V			±1.0	μΑ
ON CHARACTERISTICS (Note 3)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_{D}$	= 250 μΑ	8.0		1.4	V
Negative Threshold Temperature Coefficient	V _{GS(TH)} /T _J				3.4		mV/°C
Drain-to-Source On Resistance	-	$V_{GS} = 4.0 \text{ V}, I_{D}$) = 10 mA		1.0	1.5	
	R _{DS(on)}	$V_{GS} = 2.5 \text{ V}, I_{D}$) = 10 mA		1.5	2.0	Ω
Forward Transconductance	9 _{FS}	$V_{DS} = 3.0 \text{ V}, I_{D} = 10 \text{ mA}$			0.33		S
CHARGES AND CAPACITANCES							
Input Capacitance	C _{iss}	$V_{GS} = 0 \text{ V, f} = 1.0 \text{ MHz,}$ $V_{DS} = 5.0 \text{ V}$			21	42	pF
Output Capacitance	C _{oss}				19.7	40	
Reverse Transfer Capacitance	C _{rss}	53			8.1	16	7
Total Gate Charge	Q _{G(TOT)}				1.15		
Threshold Gate Charge	Q _{G(TH)}	$V_{GS} = 5.0 \text{ V}, V_{\Gamma}$	os = 24 V,		0.15		nC
Gate-to-Source Gate Charge	Q _{GS}	$V_{GS} = 5.0 \text{ V}, V_{E}$ $I_{D} = 0.7$	1 A		0.32		
Gate-to-Drain Charge	Q _{GD}		•		0.23		
SWITCHING CHARACTERISTICS (Note	4)						
Turn-On Delay Time	t _{d(on)}				16.7		
Rise Time	t _r	$V_{GS} = 4.5 \text{ V}, V_{E}$	on = 5.0 V,		47.9		7
Turn-Off Delay Time	t _{d(off)}	$I_D = 0.1 \text{ A}, R_0$	$_{\rm G}$ = 50 Ω		65.1		ns
Fall Time	t _f		•		64.2		7
SOURCE-DRAIN DIODE CHARACTERI	STICS		•				
Forward Diode Voltage	V_{SD}	$V_{GS} = 0 V$	T _J = 25°C		0.65	0.7	V
		$I_S = 10 \text{ mA}$	T _J = 125°C		0.45		
Reverse Recovery Time	t _{RR}	$V_{GS} = 0 \text{ V, dI}_{S}/V_{GS} = 10 \text{ V}$	dt = 8A/μs, mA		14		ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: pulse width $\leq 300~\mu s$, duty cycle $\leq 2\%$.

4. Switching characteristics are independent of operating junction temperatures.

TYPICAL PERFORMANCE CURVES (T_J = 25°C unless otherwise noted)

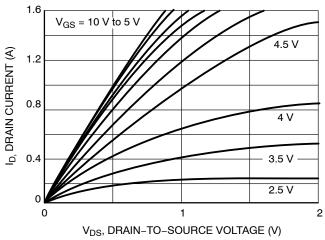


Figure 1. On-Region Characteristics

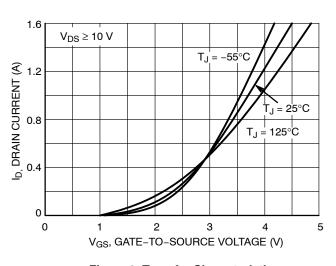


Figure 2. Transfer Characteristics

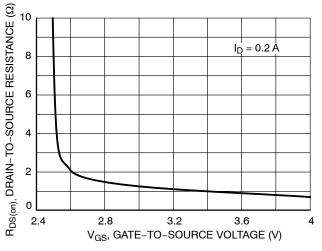


Figure 3. On-Resistance vs. Gate-to-Source Voltage

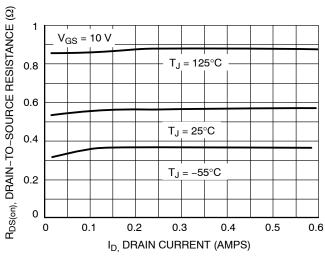


Figure 4. On–Resistance vs. Drain Current and Temperature

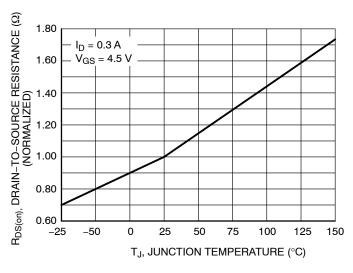


Figure 5. On–Resistance Variation with Temperature

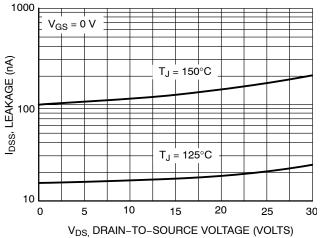


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL PERFORMANCE CURVES ($T_J = 25^{\circ}C$ unless otherwise noted)

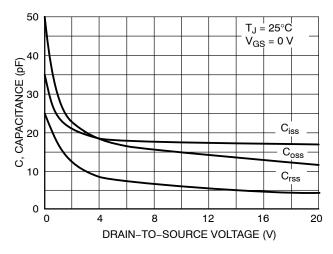


Figure 7. Capacitance Variation

Figure 8. Gate-to-Source & Drain-to-Source Voltage vs. Total Charge

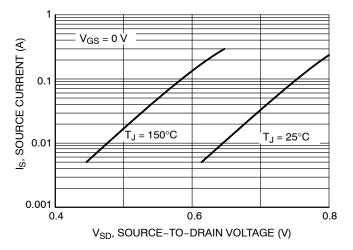


Figure 9. Diode Forward Voltage vs. Current



SOT-23 (TO-236) CASE 318-08 **ISSUE AS**

DATE 30 JAN 2018

SCALE 4:1 D - 3X b

TOP VIEW







RECOMMENDED SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

NOTES:

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH.
 MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH,

PROT	RUSIONS, OR GATE BURRS.	
		T

	M	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.89	1.00	1.11	0.035	0.039	0.044	
A1	0.01	0.06	0.10	0.000	0.002	0.004	
b	0.37	0.44	0.50	0.015	0.017	0.020	
С	0.08	0.14	0.20	0.003	0.006	0.008	
D	2.80	2.90	3.04	0.110	0.114	0.120	
E	1.20	1.30	1.40	0.047	0.051	0.055	
е	1.78	1.90	2.04	0.070	0.075	0.080	
L	0.30	0.43	0.55	0.012	0.017	0.022	
L1	0.35	0.54	0.69	0.014	0.021	0.027	
HE	2.10	2.40	2.64	0.083	0.094	0.104	
T	0°		10°	0°		10°	

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

= Date Code

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE
OT (1 F O			

SOT-23 (TO-236)

STYLE 9:	STYLE 10:	STYLE 11:	STYLE 12:	STYLE 13:	STYLE 14:
PIN 1. ANODE	PIN 1. DRAIN	PIN 1. ANODE	PIN 1. CATHODE	PIN 1. SOURCE	PIN 1. CATHODE
ANODE	SOURCE	CATHODE	CATHODE	2. DRAIN	2. GATE
CATHODE	3. GATE	CATHODE-ANODE	ANODE	3. GATE	ANODE

STYLE 15:	STYLE 16:	STYLE 17:	STYLE 18:	STYLE 19:	STYLE 20:
PIN 1. GATE	PIN 1. ANODE	PIN 1. NO CONNECTION	PIN 1. NO CONNECTION	PIN 1. CATHODE	PIN 1. CATHODE
CATHODE	CATHODE	ANODE	CATHODE	ANODE	ANODE
ANODE	CATHODE	CATHODE	ANODE	CATHODE-ANOD	E 3. GATE

STYLE 21:	STYLE 22:	STYLE 23:	STYLE 24:	STYLE 25:	STYLE 26:
PIN 1. GATE	PIN 1. RETURN	PIN 1. ANODE	PIN 1. GATE	PIN 1. ANODE	PIN 1. CATHODE
SOURCE	OUTPUT	2. ANODE	2. DRAIN	2. CATHODE	2. ANODE
3 DRAIN	3 INPLIT	3 CATHODE	3. SOURCE	3. GATE	NO CONNECTION

STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE	
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